

Amendments to the Abstract

Please replace the original Abstract with the following amended Abstract. Appendix A includes a clean copy of the amended Abstract.

In a semiconductor integrated circuit device and a semiconductor integrated circuit chip, ~~being provided for achieving small sizing and light-weight of the entire cooling structure thereof, without lowering the permissible temperature for an integrated circuit package,~~ a circuit forming layer 2, on which are formed a large number of circuits, is formed on one surface side ~~surface~~ of a plate-like semiconductor chip 101, and on the other, opposing surface side ~~thereof surface opposing to that forming the circuits thereon,~~ a heat transfer layer 15 is connected with therewith in one body. This heat transfer layer 15 is made of a material similar to that of the semiconductor chip, and ~~within an inside thereof are~~ has formed therein passage ducts 3 to build up a closed flow passage. Within this closed flow passage is enclosed an operating fluid 4, ~~such as, a water or the like,~~ and there is provided a resistor film 5 for building up a driving means, such as a resistor film, of the operating fluid, ~~in contact with the operating fluid.~~ Vibration is given to the operating fluid by the driving means, through evaporation (or bumping) due to heating by means of the resistor film 5, in a pulse-like manner, thereby transferring/diffusing a local increase of ~~temperature,~~ temperature which is generated within the circuit-forming layer 2.